

# Multiscale Modeling of Electronic Materials CRA



**Dr. Martin Berzins**  
Program Manager

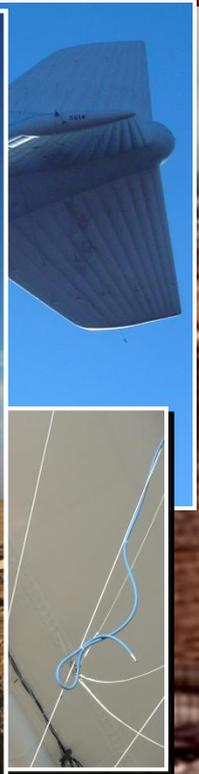


**Dr. Meredith Reed**  
Collaborative Alliance Manager

MSME/MEDE kick-off meeting 31 July, 2012



**Future Capabilities**  
will rely on the ability to specifically  
design materials for continued  
**Army Soldier superiority**  
on the battlefield



## Materials by Design

Validated multiscale & multidisciplinary modeling capability to apriori predict material structure, properties, and performance.

Three Electronic Materials Research Areas:

- Electrochemical Energy Materials
- Hybrid Photonics Materials
- Heterogeneous Metamorphic Electronic Materials

## Provide the US Army with:

- New materials and devices with unprecedented properties and capabilities
- Strategic advantage for investing and developing materials for current/future war fighter
- Reduce development time and cost
- Improved and enabling materials/systems that are in line with TeCD goals (e.g., Force Protection, Overburden, Tactical Intelligence, Sustainability/Logistics, etc.)

## FUTURE PAYOFFS

**Materials by Design**

Provide an  
**Enterprise for Innovation**

Empower  
**Unburden and Protect**



**Sensors, Devices,  
Power and Energy**

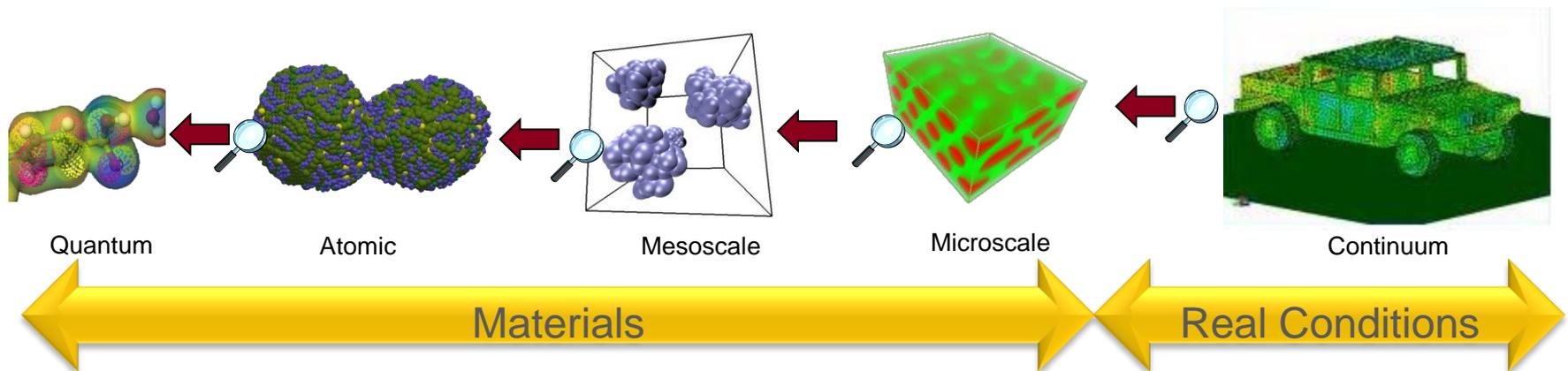
3X in energy density  
30% more efficient  
30% longer lifetimes

**Vehicle and Soldier  
Protection**

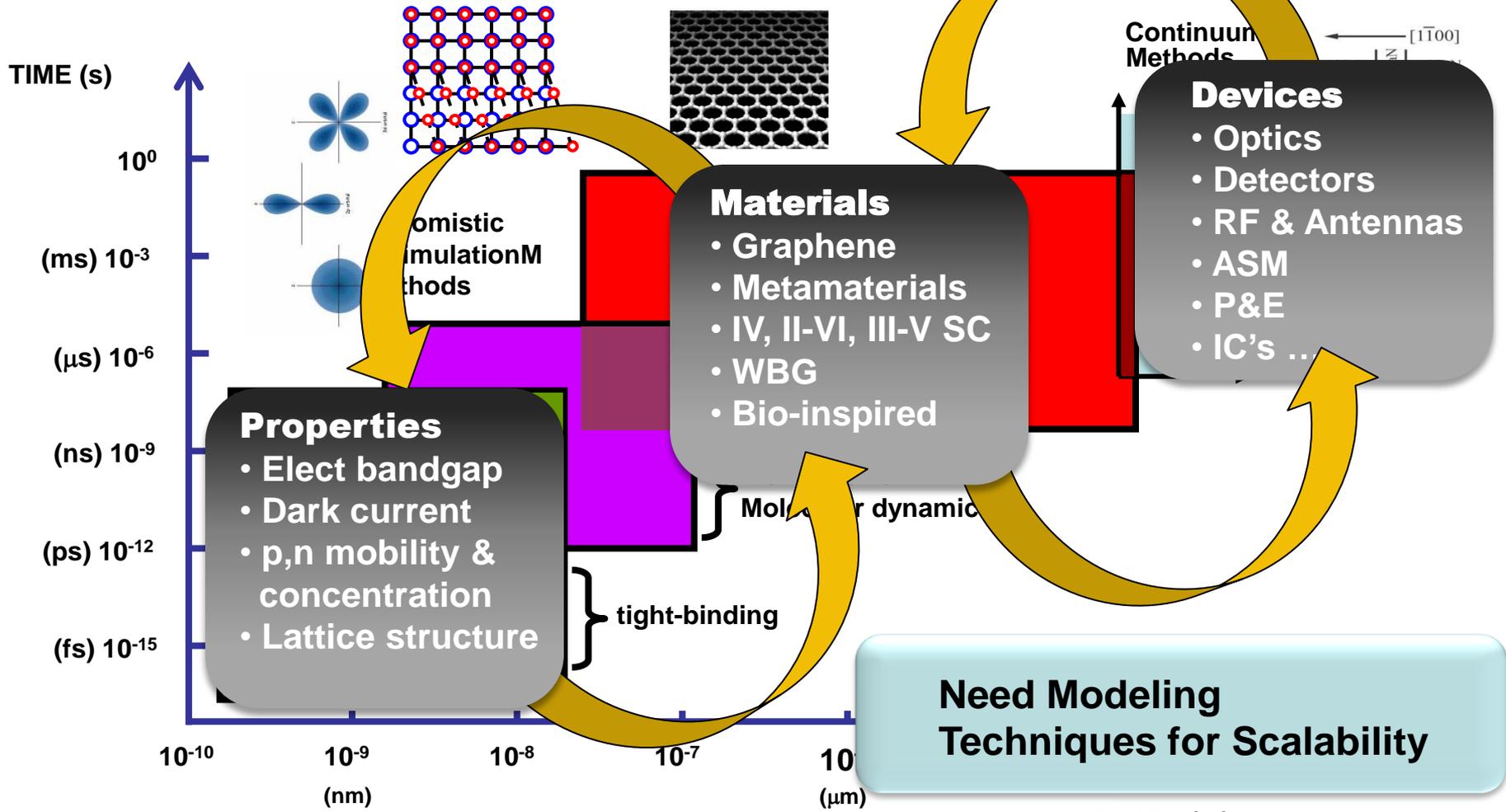
1/3 savings in weight

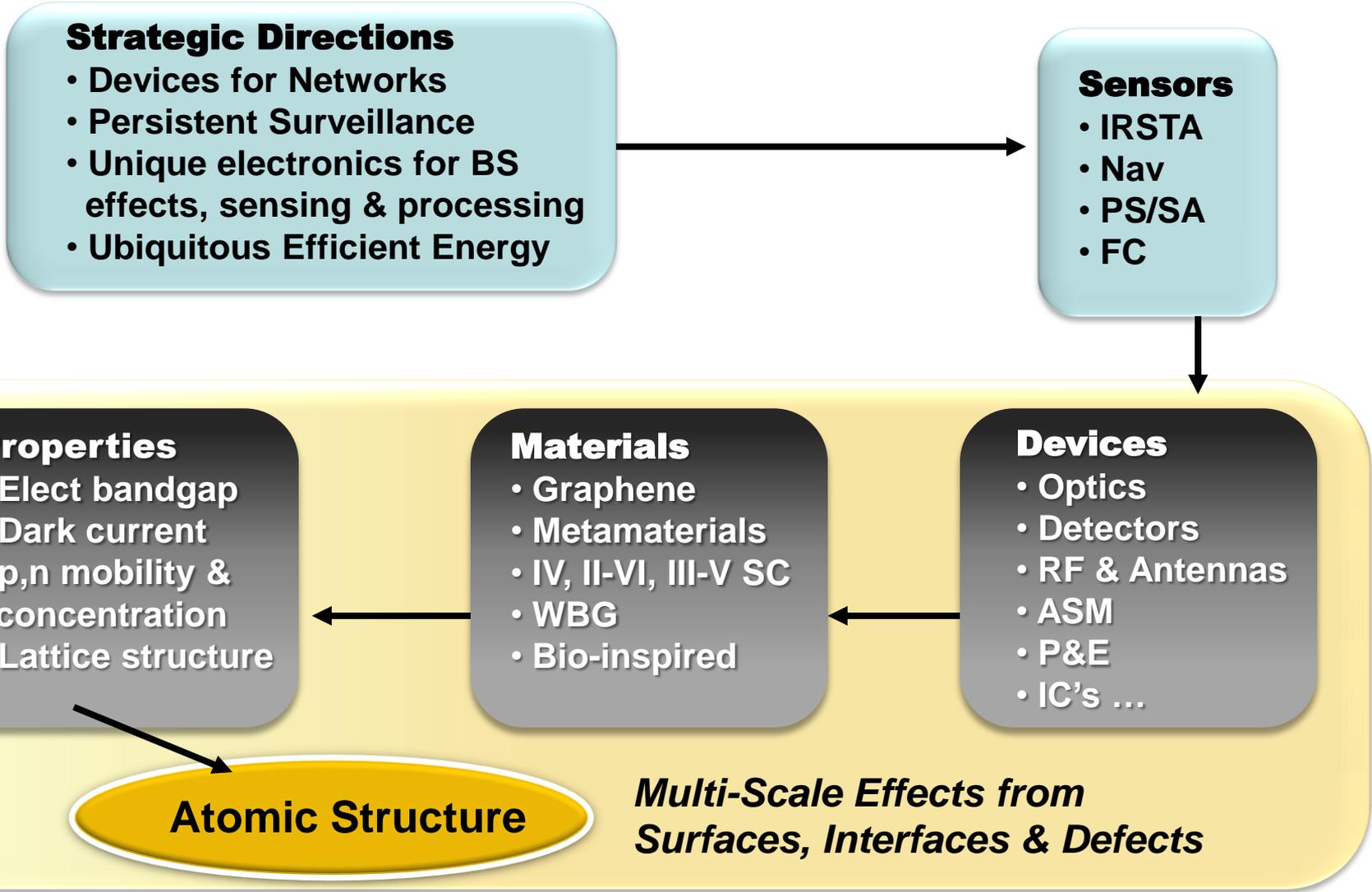
## Why Now?

- Discovery of new materials (e.g. graphene, metamaterials, plasmonics, high voltage cathodes ...)
- Need understanding and guidance for new or improved material development
- Multi-core processors → Petascale, Exascale, Graphical Processing Units (GPUs)
- Support maturation of electronic materials (IR, nano, e.g. CNT, WBG)
- Advancements in UQ and V&V



**Challenge:** Modeling a physical phenomenon from a broad range of perspectives, from the atomistic to the macroscopic and





**Materials Models Must Be Multi-Scale**

## APPROACH

*Fundamental research with a “materials by design” approach to relate the response of structural and electronic materials across critical length & time scales to specific properties*

### Electronic and Protection Materials for U.S. Army Systems

### Multiscale/Multidisciplinary Materials Design Approach

**Modeling & Simulation**

**Bridging the Scales**

**Transformational Protection & Electronic Materials**

**Synthesis & Processing**

**Advanced Experimental Techniques Validation & Verification**

**Multiscale Material Characteristics & Metrics**

## Performed for each of the Electronic Materials Research Areas

**Experimental  
Analysis  
External  
Characterization  
CRA  
Effort  
Computational  
Techniques**



**Computational  
Techniques**

- **Modeling and Simulation:** Validated multiscale modeling of electronic materials design materials and predict performance by exploiting the hierarchy of scales in a multidisciplinary environment
- **Bridging the Scales: Analysis, Theory and Algorithms:** Validated theoretical and analytical analyses to effectively define the interface physics across length scales and disciplines
- **Multiscale Modeling Material Metrics:** A comprehensive set of metrics that electronic material for each of the three Electronic Materials Research Areas defined above to enable the enhancement or creation of new electronic devices
- **Validation and Verification:** Comprehensive validated experimental capabilities bridging time and space for probing the physics and mechanisms of electronic materials and for verification and validation of multiscale/multidisciplinary physics modeling.
- **Synthesis and Processing:** Validated modeling and techniques for the synthesis and processing of Electronic Materials.

## Electrochemistry

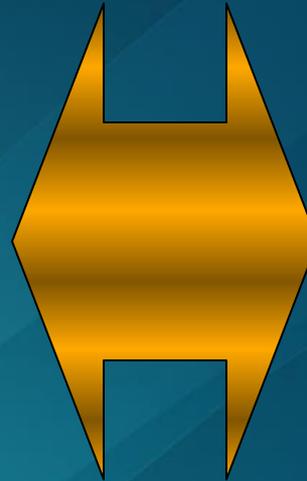
Focus on interfacial physics and chemistry; nano structures, solid-liquid interface—clear opportunities for batteries, fuel cells, etc.

## Hybrid Photonics

Interaction of photons, electrons, phonons—photonics, spintronics, plasmonics, and phonons

## Heterogeneous Metamorphic Electronics

Mixed materials, with partial ordering—includes graphene, metamaterials, nanoelectronic structures, etc.



## Cross-cutting Materials and Modeling Challenges

- **Verification and Validation/Uncertainty Quantification**
- **Bridging scales:**
  - Coarse graining
  - Adaptive mesh refinement
- **Transport:**
  - At/across interfaces
  - Electron or photon transport
  - Energy transport
  - Mass/ion transport
- **Defects:**
  - Defects, surfaces or interfaces
  - Strain
  - Impurities, Vacancies, Interstitials
  - Point Defects
  - Compositional inhomogeneities

# Computationally-guided Design of Energy Efficient Electronic Materials (CDE<sub>3</sub>M) Organizational Chart

Research Management Board (RMB)

Collaborative Alliance Manager (CAM)

Dr. Meredith L. Reed



Program Manager (PM)

Dr. Martin Berzins



Assistant Program Managers (APM)

Dr. Dmitry Bedrov

Dr. Mike Kirby

Alliance Executive Committee (AEC)

Feng Liu

Enrico Bellotti

Michael Shur

Martin Berzins

## PROJECTS (Teams)

### A. Electrochemical Energy Devices

(Bedrov)

**A1:** Lithium Ion Batteries

**A2:** Alkaline Membrane Fuel Cells

### B. Hybrid Photonic, Spintronic Materials

(Bellotti)

**B1:** Materials Modeling for Multi-spectral Detectors

**B2:** Modeling for Light Emitters

**B3:** Defects, Interfaces and Dislocation Studies

**B4:** Plasmonics and Metamaterials

### C. Heterogeneous Metamorphic Electronics

(Shur)

**C1:** Electronic Structure and Transport in Layered 2D Heterostructures and Devices

**C2:** Heterogeneous Systems for THz Electronics

**C3:** Thermal Transport in Hetero-geneous Systems

### D. Crosscutting Themes

(Kirby)

### SCALE BRIDGING

(Task Forces)

**Adaptive Mesh Refinement**

(Berzins)

**Course-graining**

(Bedrov)

**Consecutive Coupling**

(Molinero)

**Concurrent Coupling**

(Karniadakis)

**VV and UQ**

(Kirby/Karniadakis)

### METHODS

(Groups)

**Ab Initio (AI)**

(Galli)

**Particle Based Simulations**

(van Duin)

**Continuum Modeling**

(Dal Negro)

**CAM:** Meredith Reed

**TECHNICAL LEADS**

**Electrochemistry**

- Oleg Borodin (Batteries)
- Kyle Grew (Fuel Cells)

**Heterogeneous  
 Metamorphic**

- Terrance O'Regan

**Hybrid Photonics**

- Sergey Rudin



**ARL Scientists/Collaborators**  
 (both modelers and experimentalists)

Richard Jow  
 Cindy Lundgren

Deryn Chu  
 Jan Allen

Frank Crowne  
 Pankaj Shah  
 Madan Dubey

Glen Birdwell  
 Amir Zaghoul  
 Steve Weiss

Greg Rupper  
 Priyalal Wijewarnasuriya  
 Michael Wraback  
 Greg Garrett  
 Anand Sampath

Ken Jones  
 Randy Tomkins  
 Greg Brill  
 Grace Metcalfe



Spend About \$3M per year including cost share

**Area A: Electrochemical Energy**

Dmitry Bedrov  
 Martin Berzins  
 Feng Liu  
 Mike Kirby  
 Valeria Molinaro

Giulia Galli

UC Davis

University of Utah

George Karniadakis

Brown

**Area B :Hybrid Photonics**

University of Utah MSME CRA

Adri van Duin

Penn

Enrico Bellotti  
 Luca Del Negro  
 Martin Herbordt

Boston University

Politecnico di Torino

Rensselaer Polytechnic Institute

Harvard

Efthimios (Tim) Kaxiras

Giuseppi Vecchi  
 Francesco Bertazzi

Michael Shur, Vincent Meunier ,  
 Saroj Nayak, Pawel Koblinsky,

**Area C: Heterogeneous Metamorphic Electronics**

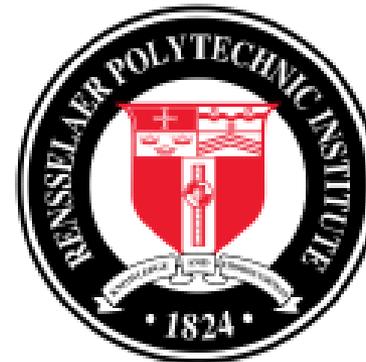
# Multiscale Modeling of Electronic Materials (MSME) Collaborative Alliance Members



## LRO: University of Utah

Program Manager: Martin Berzins  
Professor School of Computing and SCI  
Institute Scale Bridging, Adaptive Mesh  
Refinement

Assistant Program Managers :  
Dmitry Bedrov Research Associate  
Professor Materials  
Mike Kirby Associate Professor  
School of Computing and SCI Institute



## Rensselaer Polytechnic Institute (RPI)

Principal: Michael S. Shur  
Professor of Electrical, Computer and  
Systems Engineering, and Professor of  
Physics, Applied Physics and Astronomy  
Director, NSF RPI Connection One  
IUCRC Center  
Heterogeneous Metamorphic Electronics



## Boston University

Principal: Enrico Bellotti  
Associate Professor of Electrical and  
Computer Engineering Department  
Director, Computational Electronics  
Laboratory (CEL)  
Hybrid Photonics Materials

## US Army Research Laboratory

Collaborative Alliance Manager: Meredith L. Reed



ARL brings expertise in electronic, electro-optical and electrochemical materials and devices design, modeling, synthesis and processing, characterization, multiscale modeling and computational tool development.

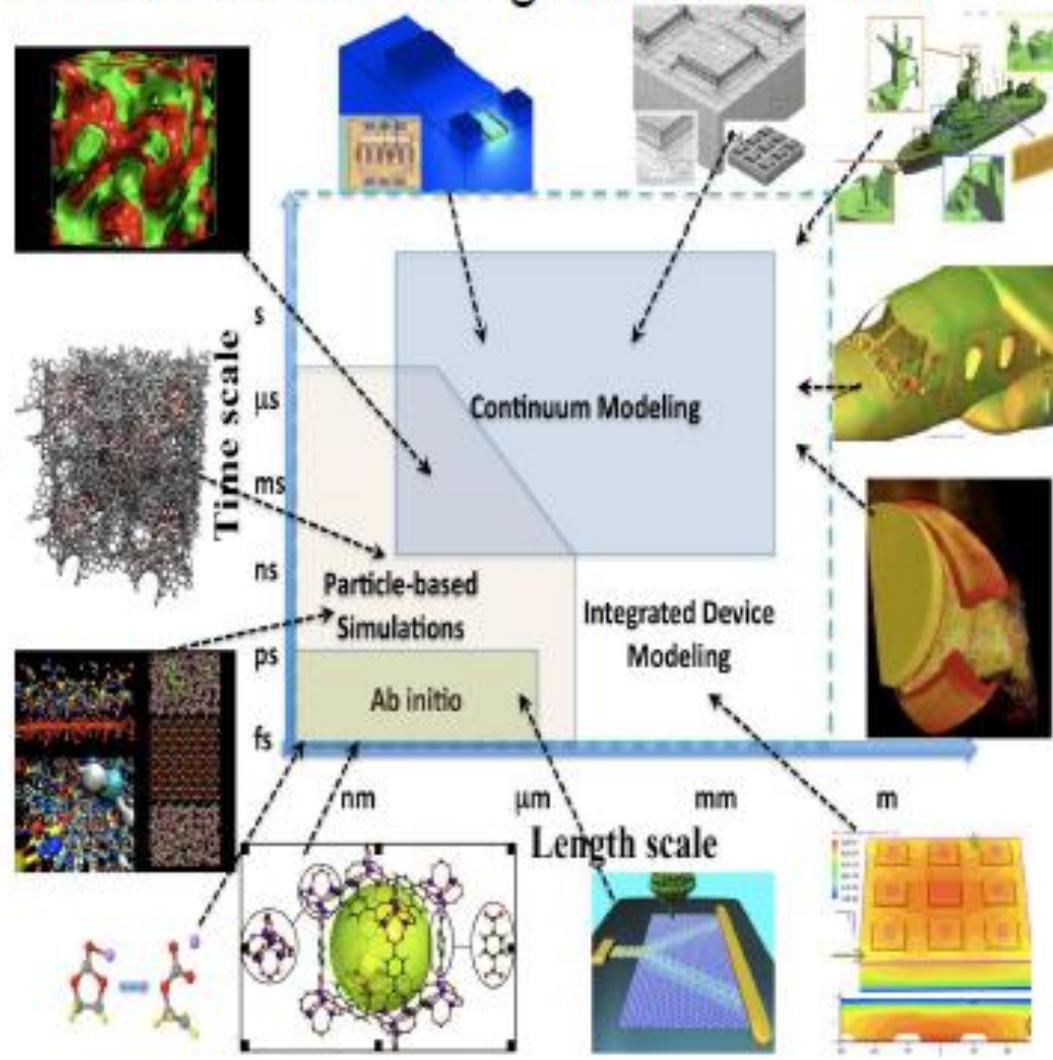
Advances in MSME application areas require not only fundamental materials research but application of cross-cutting multiscale and multidisciplinary methods.

**Outline:**

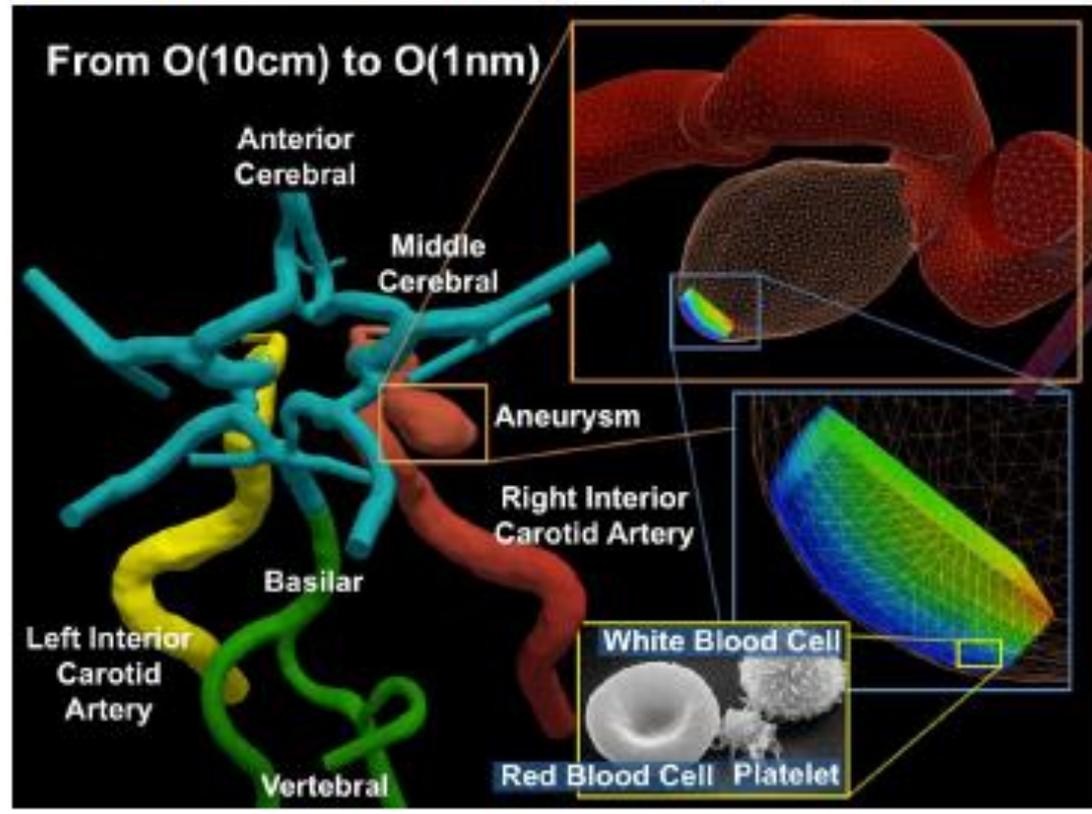
The state of the art in multi-scale modeling and VVUQ

Overview of three materials areas (Bedrov, Bellottii and Shur ) and cross-cutting methods (Kirby Galli).

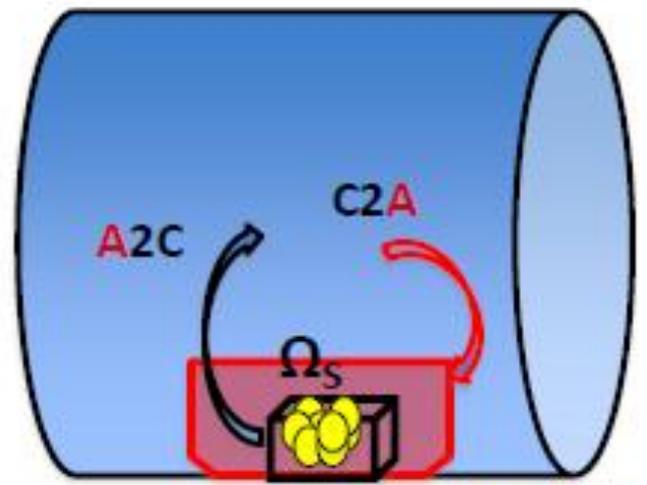
Detailed material applications  
Wednesday AM



Interfacing MD models of platelets with continuum models of blood flow in modeling aneurysm rupture - Grinberg and Karniadakis



**CONTINUUM**  
*NekTar*



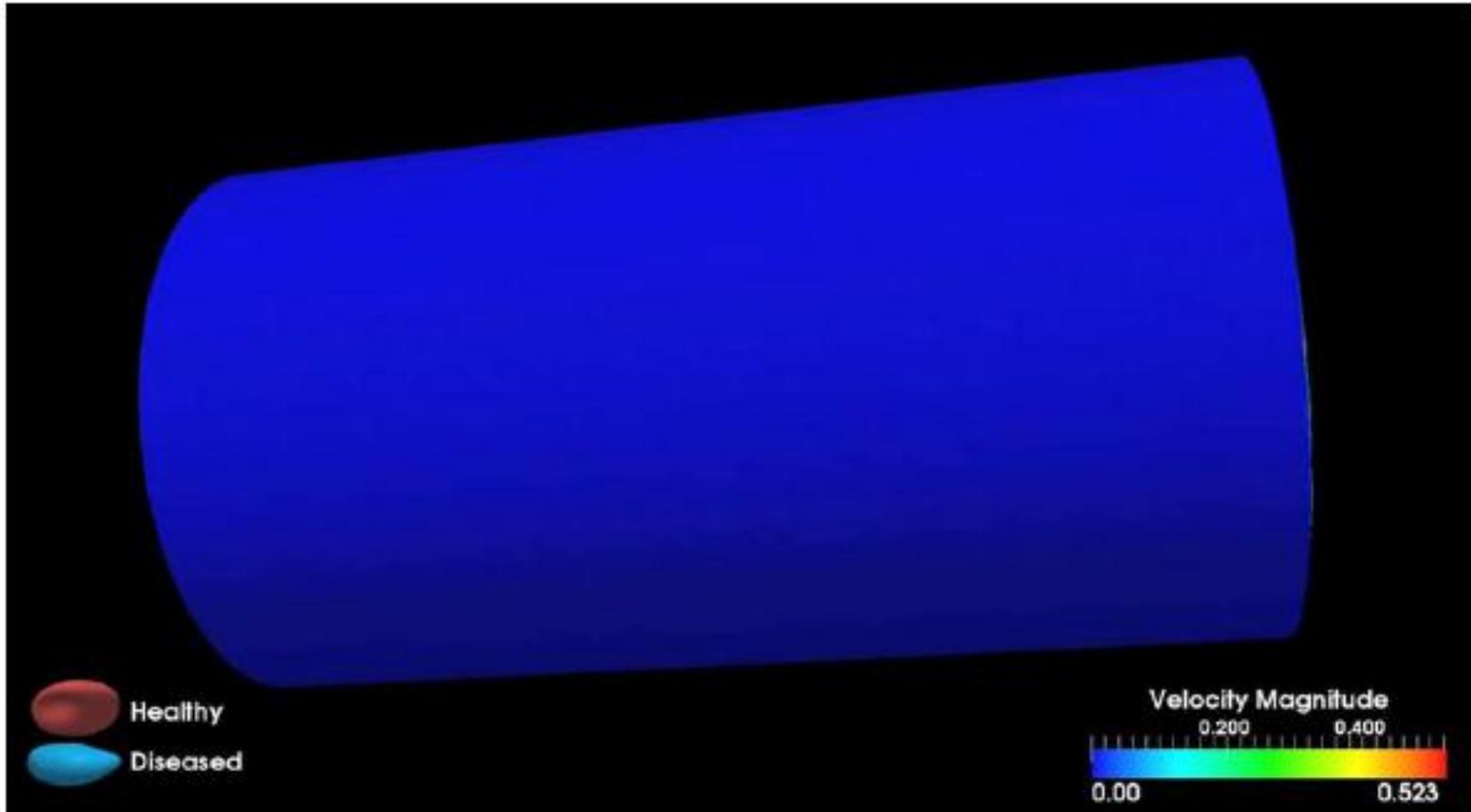
**ATOMISTIC**  
 (DPD-LAMMPS)

Dissipative Particle Dynamics particles are agglomerations of MD particles

Platelet model in atomistic domain  $\Omega_s$

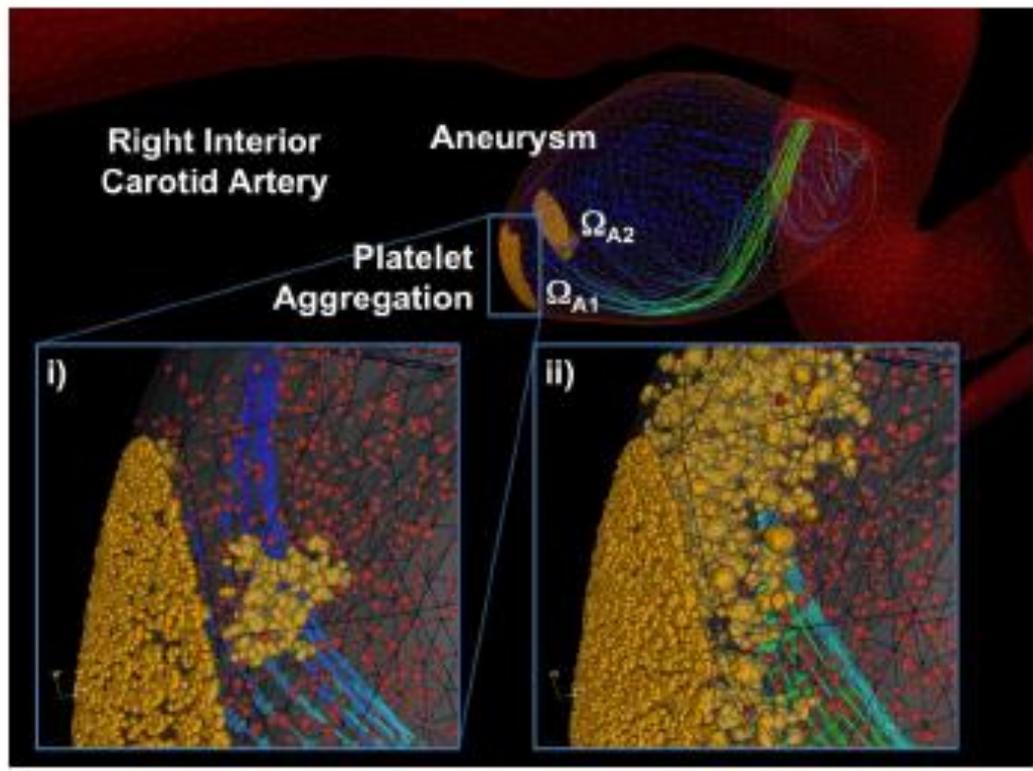
A2C are atomistic to continuum boundary conditions

# Multiscale Model including Continuum Atomistic DPD interactions



Source Leo Grinberg

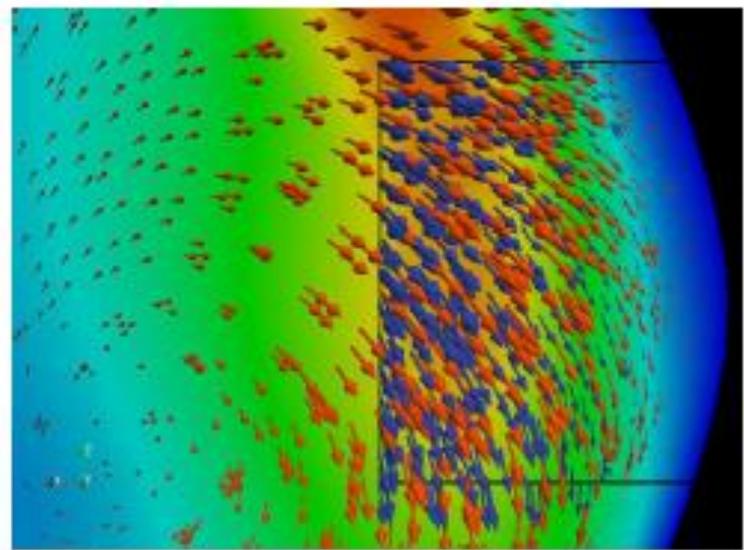




Clot Formation

Progression of clot

Yellow dots are active platelets, red dots are inactive platelets



Continuum velocities

Particle Velocities

Ncore (DPD-LAMMPS+Nektar)	CPU-time for 4000 steps	Speedup
8 Racks (32,768 cores)	7952 s	1.0
72 Racks (294,912 cores)	733 s	10.85

We now compute very complex solutions to ever more challenging computational modeling problems. **Due diligence requires that we ask:**

How accurate is the model that we use?

How accurate is the solution to that model?

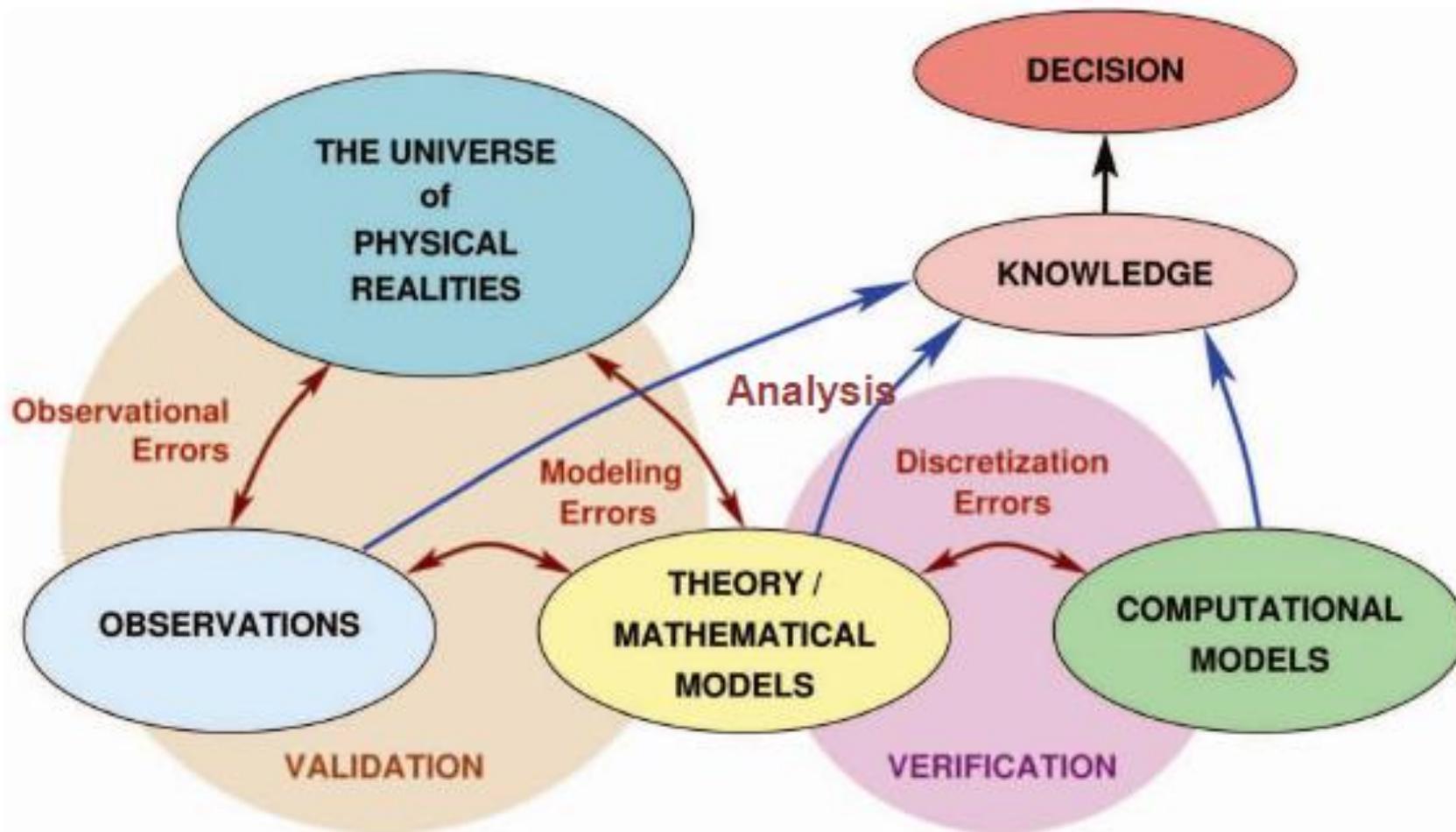
How does the solution vary if the model does?



Leads to an increasing focus on **VVUQ**  
**V**erification **V**alidation and **U**ncertainty **Q**uantification

DOE NNSA has promoted work on this... but

-- "VVUQ turned out to a little bit harder than we thought." PSAAP meeting 2011



We validate mathematical models and **verify the software** that implements them

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Model Validation

Assess physics model against experimental data

Code Verification

Assess algorithms and their implementation vs. exact solutions

Solution Verification

Estimate computational (discretization) error in numerical solution

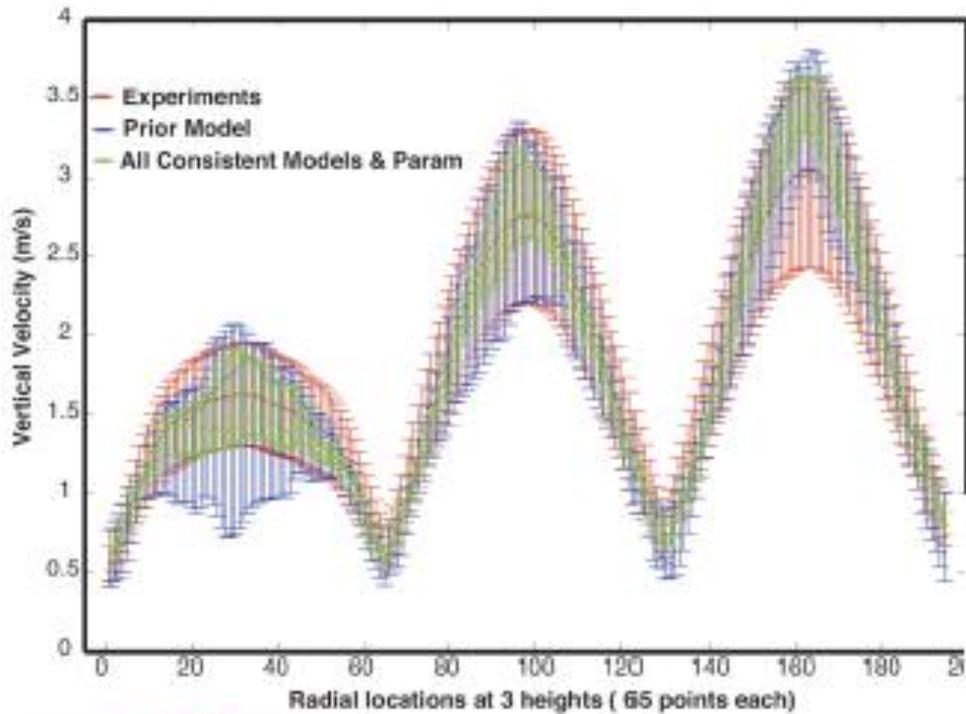
Sensitivity Analysis/  
Uncertainty  
Quantification

Assess sensitivity or uncertainty of answer to input parameters  
Aleatory uncertainty – randomness in model or parameters  
Epistemic uncertainty – due to lack of knowledge.

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- **Regular meetings**
- **Regular visits between ARL and Consortium, in both directions**
  - **Faculty/ARL SME Staff rotations**
  - **Short term and Long term visits, internships, part-time work at ARL for Phd's, postdocs, students at ARL**
- **Development of computational infrastructure for sharing data**
- **Establish collaborative space, both at Consortium and at ARL**
- **Establish collaboration between MSME, MEDE and ARL Enterprise in cross-cutting areas**
- **Educational efforts**
  - **Seminar series (one credit hour each) at BU, UU and RPI**
  - **Training in computational modeling and parallel computing**
    - **Boston University Scientific Computing and Visualization group**
- **MSME Corporate Partnership Program - currently ~50 members**

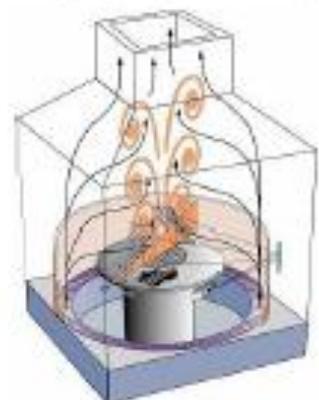
# VVUQ State of the Art with Utah Uintah Buoyant Helium Plume Model



**Red** is experimental uncertainty

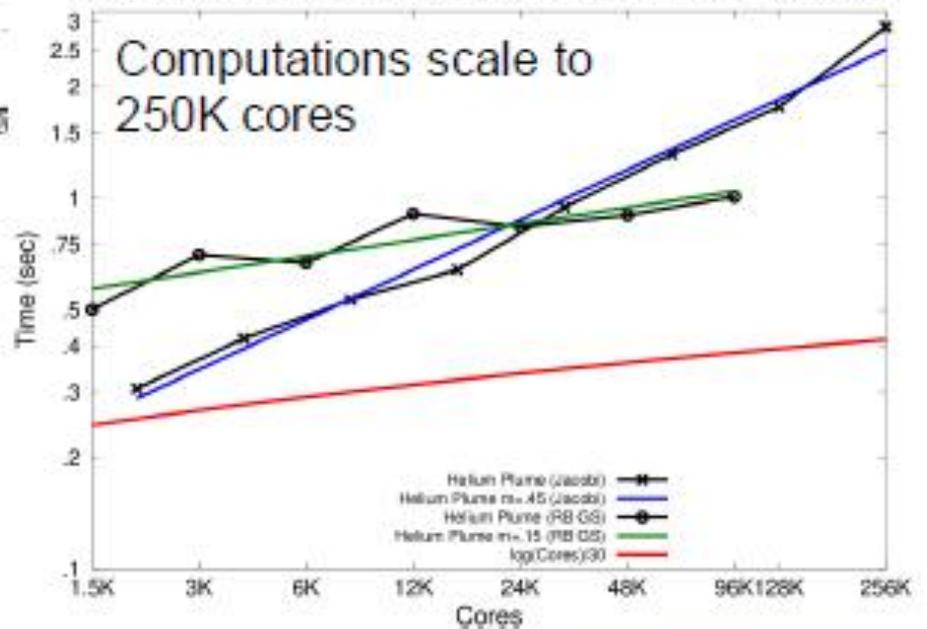
**Blue** is uncertainty region from simulation

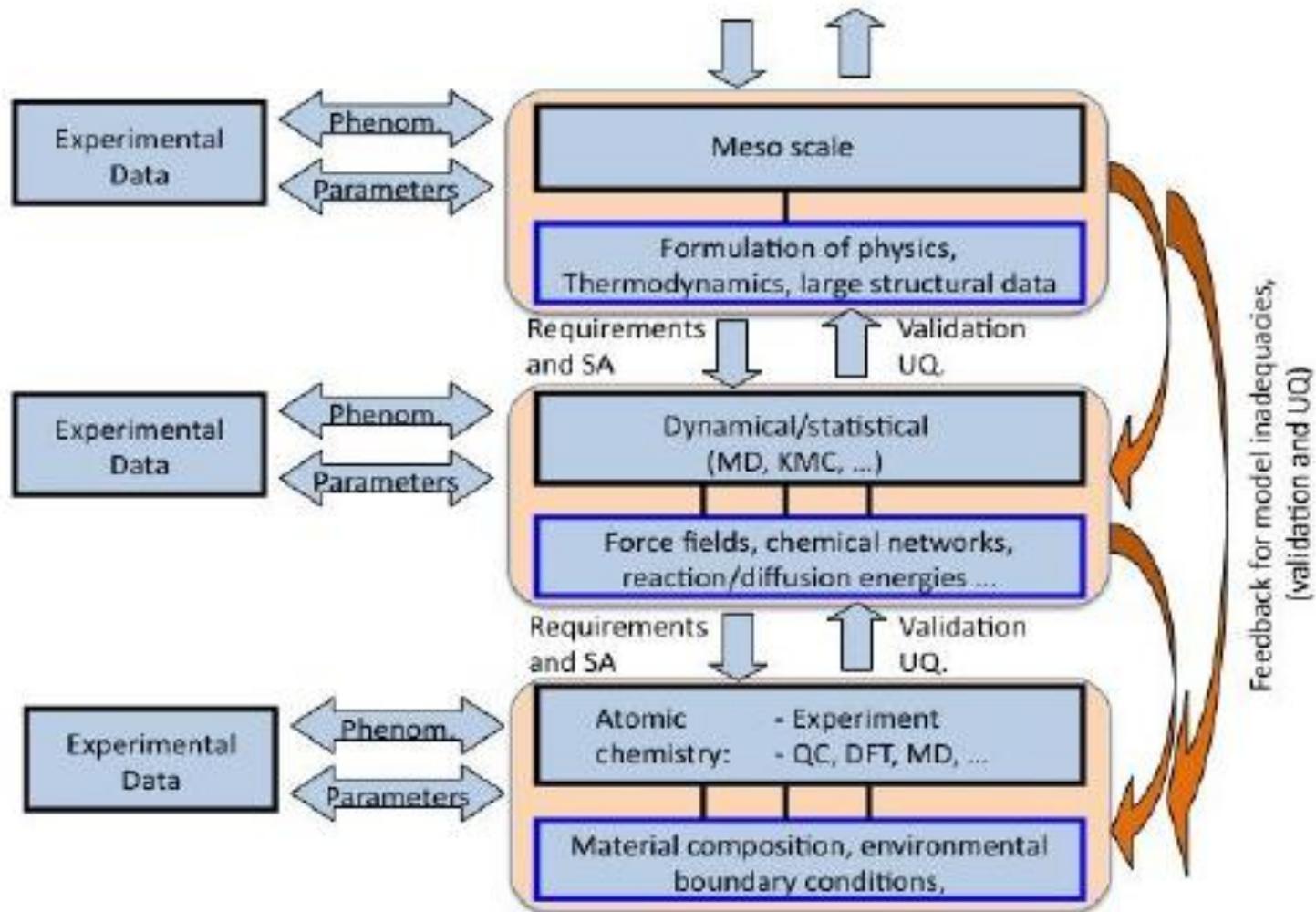
**Green** is uncertainty in vertical velocity consistent with experimental data and input parameters



Sources: Smith Schmidt

Scalability of the Linear Solver Using Jacobi and Red-Black Gauss Seidel





We need to understand sensitivity of meso scale simulation to e.g. DFT

## Area A: Electrochemical Energy Devices

**Projects:**            **A1 – Lithium Ion Batteries**  
                              **A2 – Alkaline Membrane Fuel Cells**

### Materials Design:

Dmitry Bedrov – molecular and coarse-grained simulations

Adri van Duin – reactive molecular simulations

Tim Kaxiras – multiscale modeling and ab initio methods

Valeria Molinero – molecular and coarse-grained simulations

### Crosscutting Efforts:

Martin Berzins – continuum level modeling, computational infrastructure

Mike Kirby – uncertainty quantification and coarse-graining algorithms

George Karniadakis – uncertainty quantification in multiscale modeling

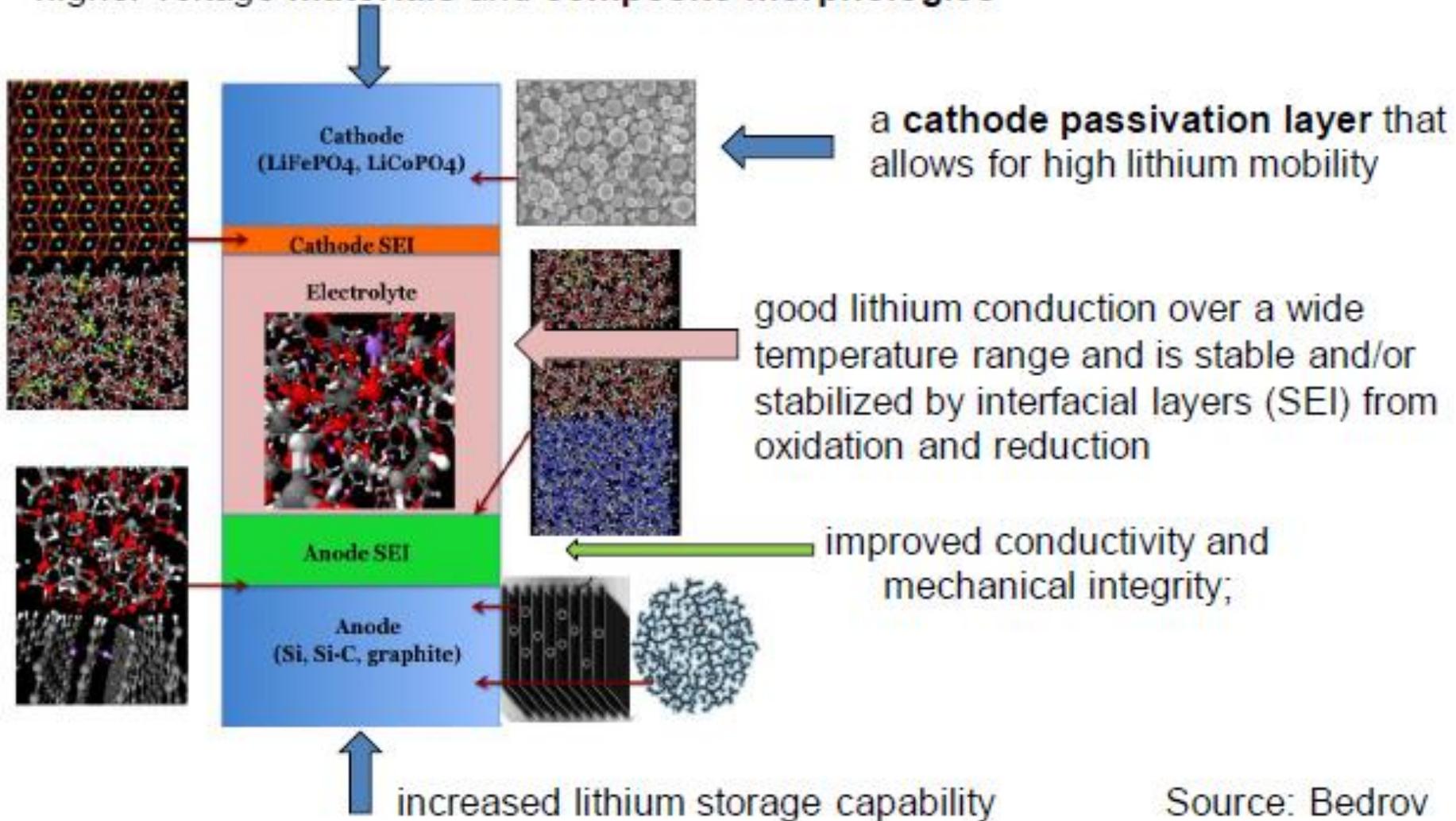
Giulia Galli – ab initio density functional calculations

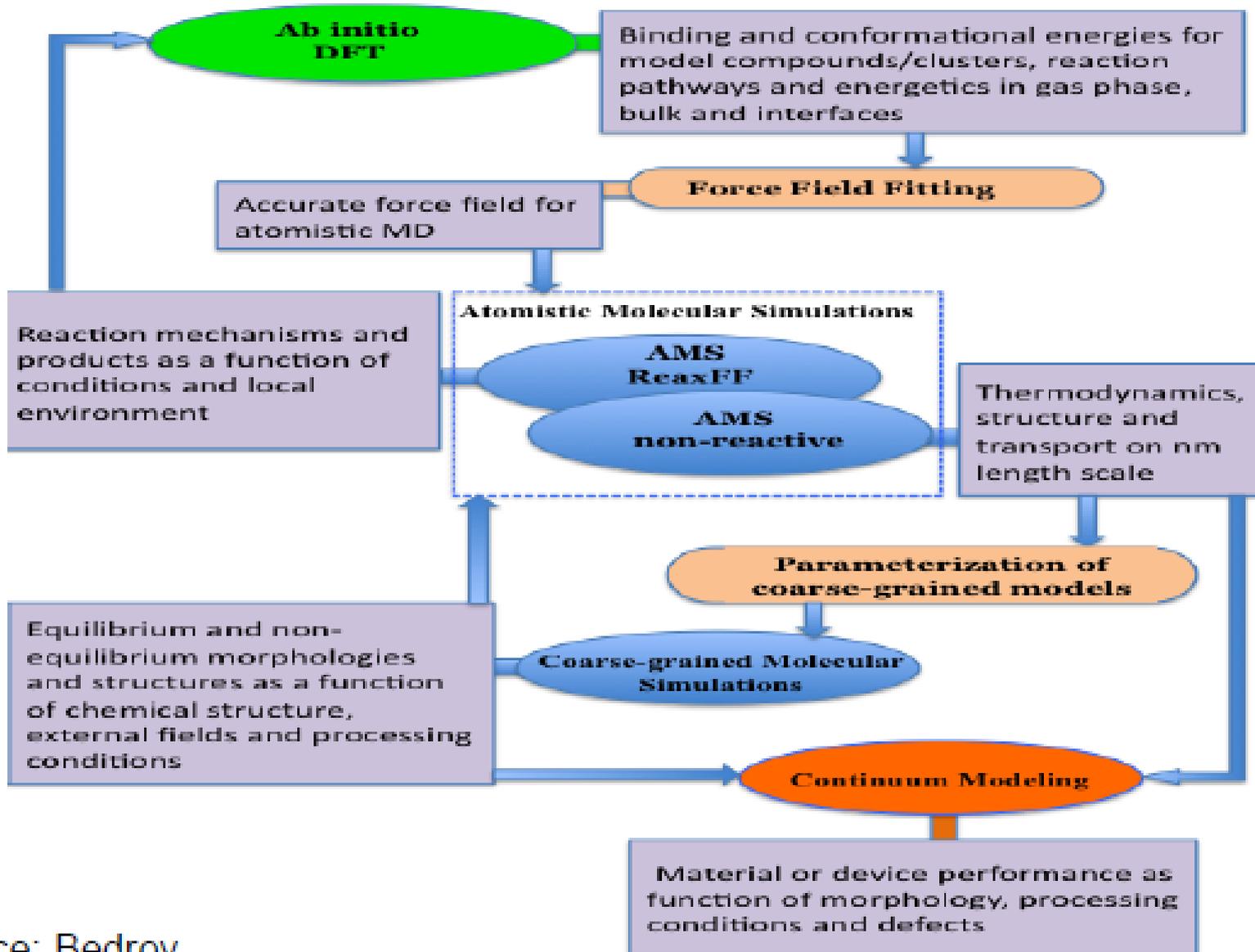
### ARL Members:

Oleg Borodin, Richard Jow, Cynthia Lundgren, Kyle Grew, Deryn Chu

## Next generation needs:

higher voltage **materials** and **composite morphologies**





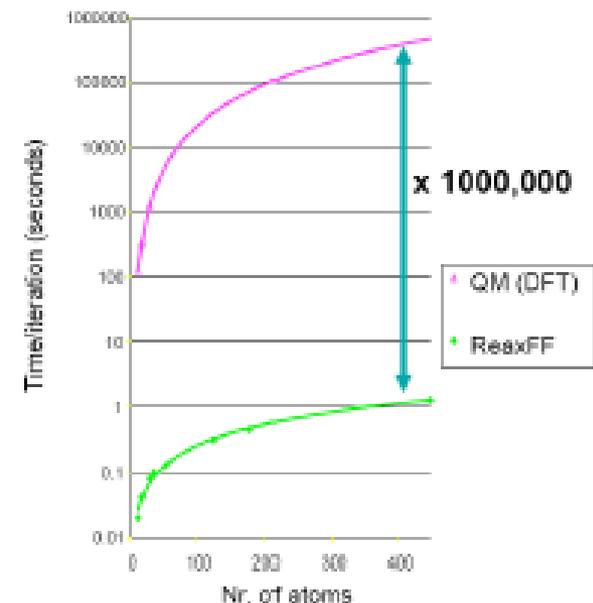
### Area A : Two – Year Goals:

- Accurate molecular simulations of electrochemistry (ReaxFF or/and DFT)
- Multiscale modeling of molecular self-assembly (SEI, alkaline membrane)
- UQ-driven methodologies for coarse-graining and scale bridging
- Validation & Verification of selected methods and models.
- Computational framework for multiscale and multiphysics modeling (Uintah)

### Five – Year Goals:

- Tools for high through put screening of materials
- Virtual design of advanced novel materials
- Strategy and tools development to address processing and fabrication conditions

Source: Bedrov, van Duin



## Area B - Hybrid Photonics Materials

### Projects:

- B1 – Material Modeling for Multi-Spectral Detectors
- B2 – Material Modeling for Light Emitters
- B3 – Defects, Interfaces and Dislocation Studies
- B4 – Plasmonics and Metamaterials

### Organizational Team Members:

- Enrico Bellotti (Area Lead)
- Luca Dal Negro
- Martin Herbordt
- Michael Shur
- Efthimios Kaxiras
- Francesco Bertazzi
- Giuseppe Vecchi
- Giulia Galli

### ARL Team Members:

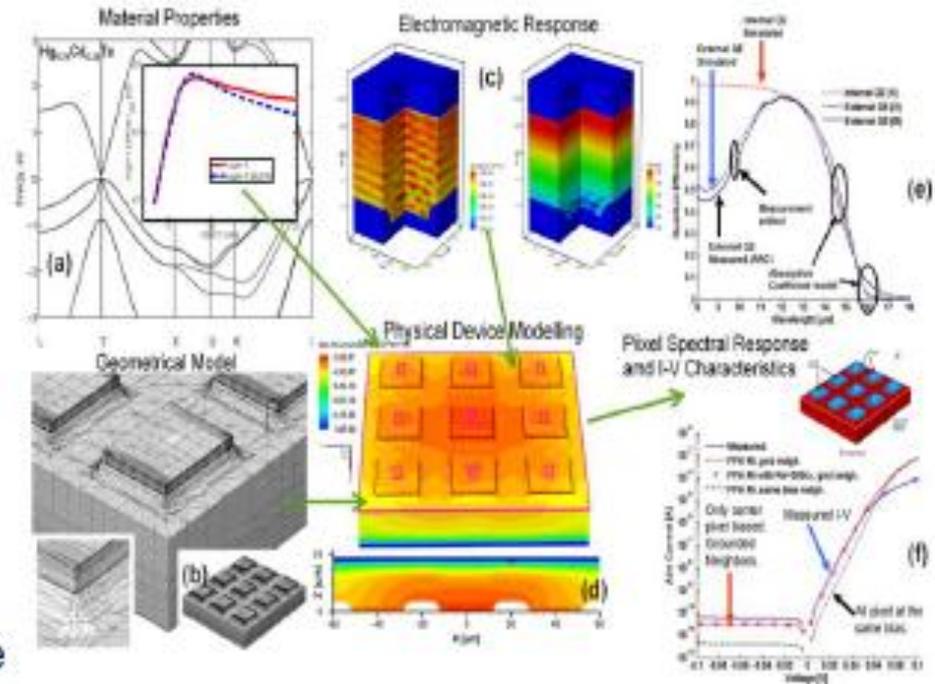
- Michael Wraback
- Sergey Rudin
- Greg Ruppert
- Ken Jones
- Randy Tompkins
- Meredith Reed

State of the art material + simulation methods for:

**B1 - Material Modeling for Multi-Spectral Detectors:** next generation of materials and device structures for detectors e.g high operating temperature IR for night vision. Year 2 goal :Comprehensive microscopic models of III-Nitrides complex alloys to be used in device simulation.

**B2 - Material Modeling for Light Emitters:** High efficiency LEDs for lighting applications and UV LEDs for bio-chemical threat detection. Comprehensive microscopic model of the non- radiative and radiative processes in light emitters structures

## Multiscale Modeling for IR Materials and Pixel Arrays Models



**B3 - Defects, Interfaces and Dislocation Studies:**

Comprehensive **microscopic behavioral models of defects and dislocations in GaN and AlGaN for device simulation – Year 2 goal:**

understand /engineer the effects of materials' non-idealities on power electronics and optoelectronics devices.

**B4 – Plasmonics and Metematerials:**

engineer materials with novel electromagnetic functionalities. E.g for UV radiative rate engineering. enhanced light-matter coupling. **Year 2 goal:**

Design the first UV plasmonic III-nitrides lasers and LEDs structures with controllable radiation rates, far-field profiles and emission time dynamics.

- All projects – Transfer simulation tools to ARL for evaluation and engage in– V&V procedures
- 5 years goals also defined

## Area C: Heterogeneous Metamorphic Electronics

### Projects:

- C1 – Graphene Based Electronics
- C2 – Heterogeneous systems for THz Electronics
- C3 – Thermal Transport in Heterogeneous systems

### Organizational Team Members:

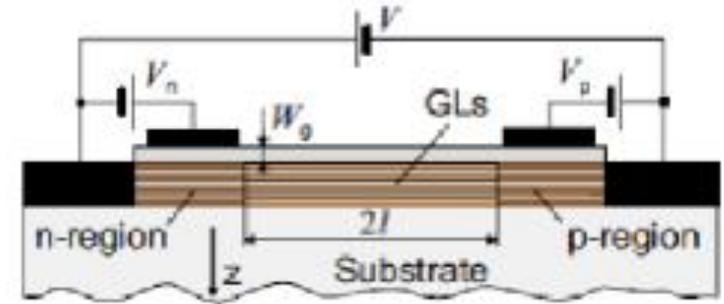
- Michael Shur (Area Lead)
- V. Meunier
- S. Nayak
- P. Keblinski
- E. Bellotti
- F. Liu,
- Giulia Galli
- T. Reinecke

### ARL Team Members:

- T. O'Reagan
- S. Rudin
- F. Crowne
- M. Wraback
- M. Dubey

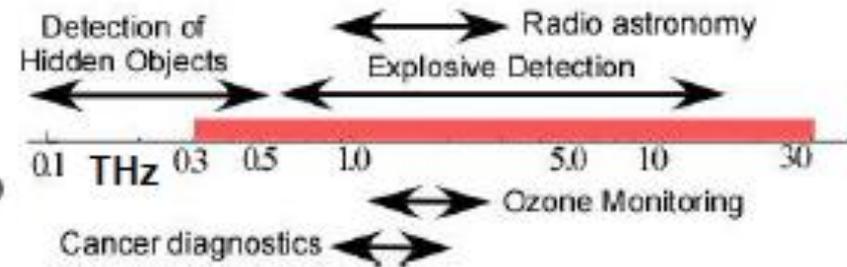
## C1. Graphene Based Electronics

2D-crystals have enormous advantage for sensing applications (going beyond CMOS)



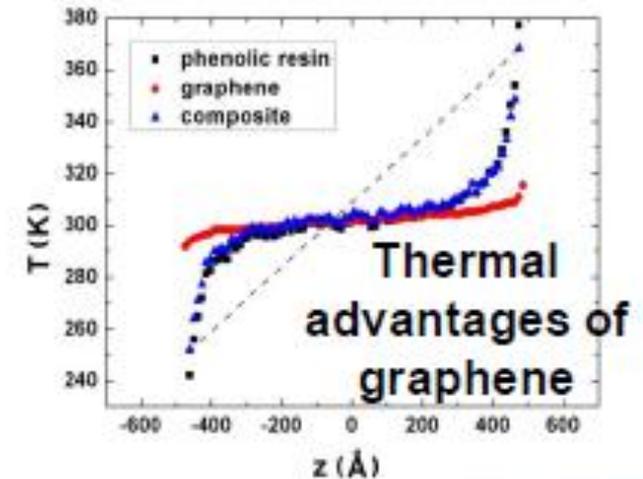
## C2. Heterogeneous systems for THz Electronics

Heterogeneous systems may help close famous THz gap opening applications in cancer detection, home land security, etc



## C3. Thermal Transport in Heterogeneous systems

Thermal transport determines an ultimate limit for performance of most semiconductor devices and circuits



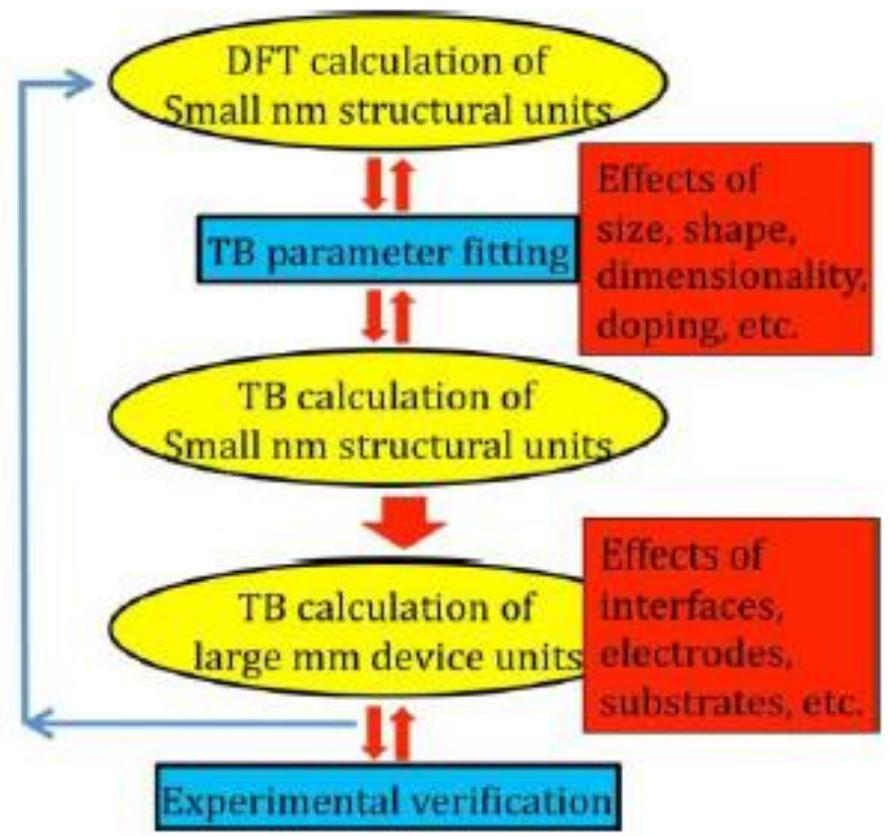
## Technical Challenges

Task C1-1: Modeling of graphene transistors (**Shur**) using DFT and Tight Binding methods

Task C1-2: Transport properties of graphitic nanoribbons attached to metallic electrode (Iron). (**Meunier**)

Task C1-3. Role of dielectrics and substrates in graphene electronics (**Nayak**)

Task C1-4. Modeling of graphene hetero-layer junctions and design of flexible keypad (**Liu**)



Multiscale modeling for Graphene-based Electronics

## Area C: Heterogeneous Metamorphic Electronics

### 3-year goals

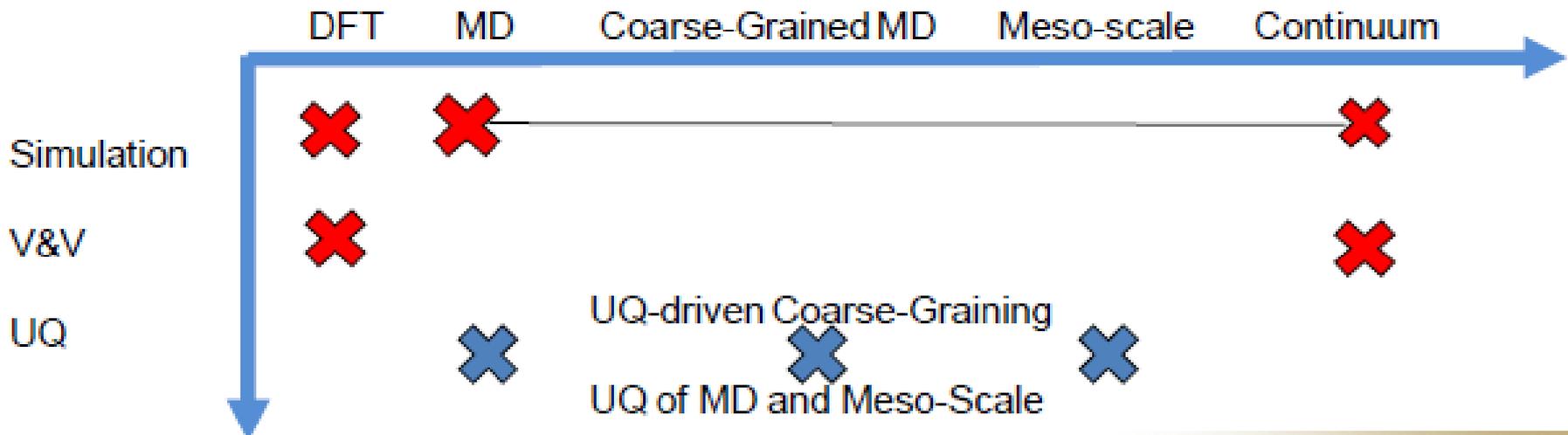
Thrust	Task	Goal
C1. Graphene Based Electronics	C1-1: Modeling of graphene transistors ( <b>Shur</b> )	Compact graphene transistor model
	C1-2: Transport properties of graphitic nanoribbons ( <b>Meunier</b> )	First-principles modeling of realistic interface with metallic nanoelectrodes
	C1-3. Role of dielectrics and substrates in graphene ( <b>Nayak</b> )	Role of dielectrics and substrates on electronic structure of graphene systems
	C1-4. Modeling of graphene hetero-layer junctions ( <b>Liu</b> )	
C2. Heterogeneous systems for THz Electronics	C2-1: Theory of THz plasmonic graphene laser ( <b>Shur</b> )	Model of THz plasmonic graphene laser
	C3-1: Molecular dynamics simulations of thermal transport ( <b>Keblinski, Galli, Bellotti, Reinecke</b> )	Predictive models of thermal conduction as a function of defect type, density and interfacial structure and bonding
C3. Thermal Transport in Heterogeneous systems		

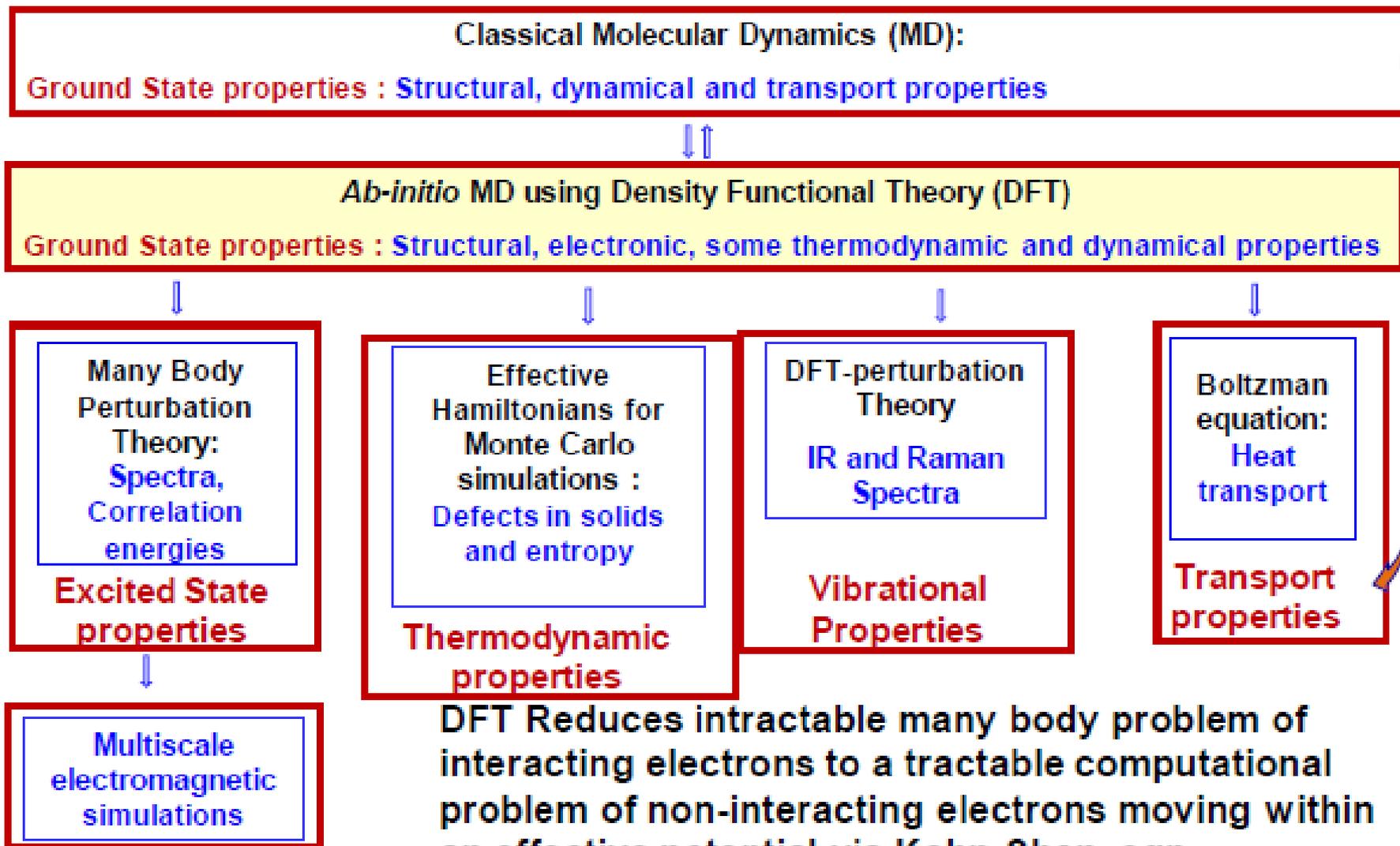
## Uncertainty Quantification (UQ) / Coarse-Graining Software Infrastructures: UintahX Density Functional Theory (DFT)

### Team Members:

- Mike Kirby (Area Lead) – Algorithms VVUQ
- Martin Berzins – Adaptive Meshing Petascale and Exascale Computing, Verification and Error estimation
- Giulia Galli – DFT Development and simulation
- George Karniadakis – gPC UQ Methodology and Multiscale Bridging

### Methods By Scale

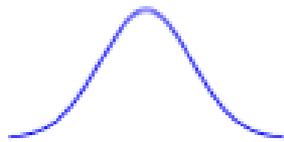




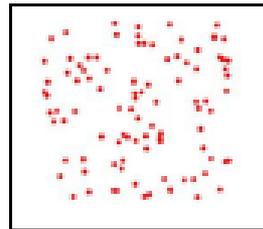
DFT Reduces intractable many body problem of interacting electrons to a tractable computational problem of non-interacting electrons moving within an effective potential via Kohn-Shan eqn

Inputs:

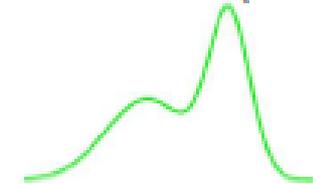
- Initial conditions
- Boundary conditions
- Model parameters



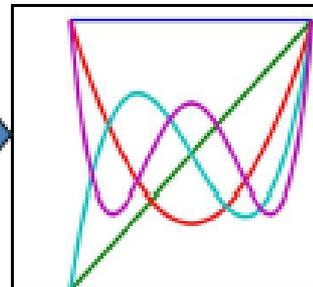
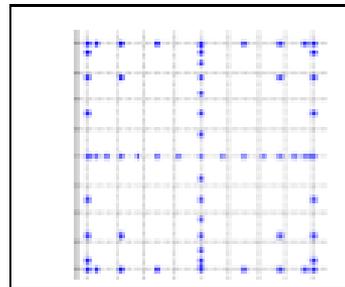
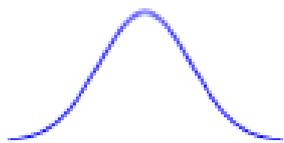
Monte Carlo Sampling of Solver



Distribution of output quantity Of interest (QOI)



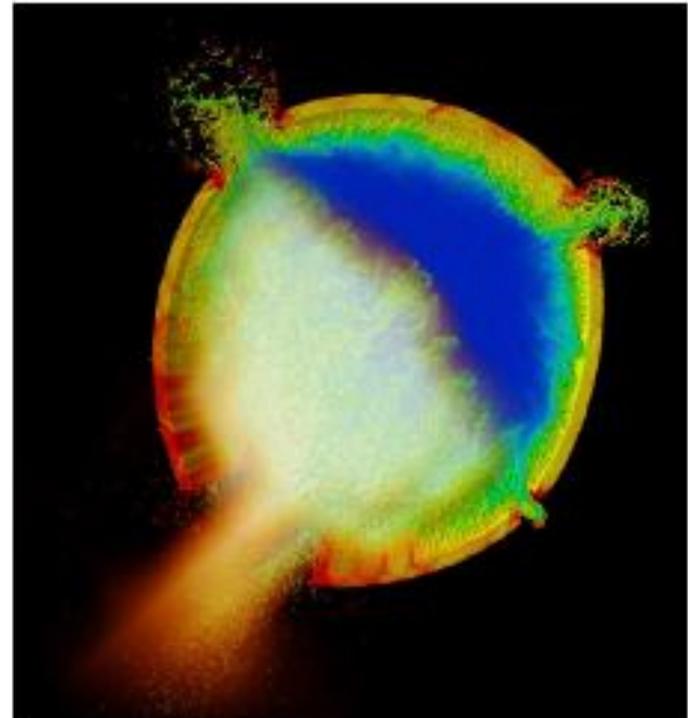
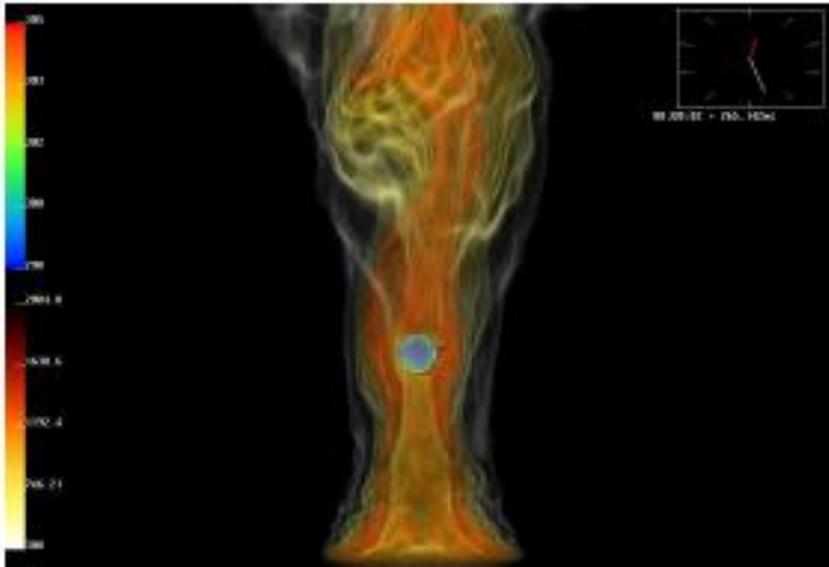
Input probability distribution for parameters



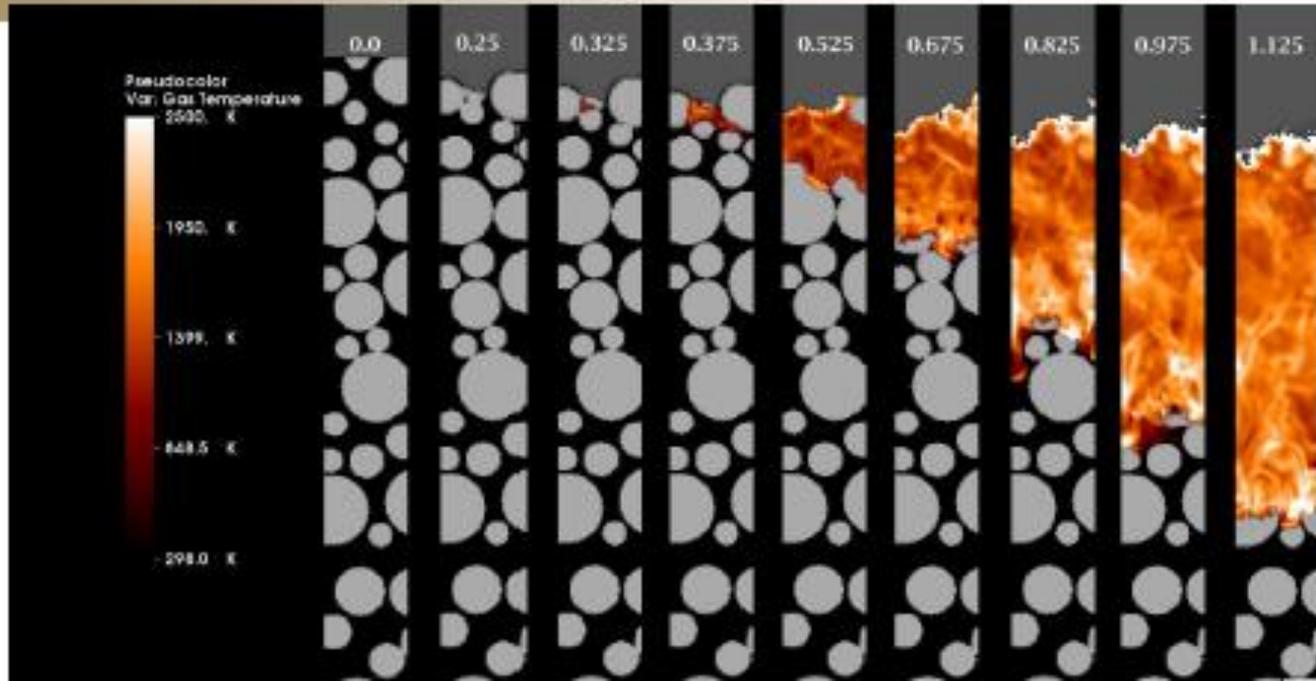
Judicious sampling of solver solution at quadrature points

Use polynomial chaos representation of uncertainty  
**Generalized Polynomial Chaos**

Steel container containing PBX 9502 in A pool fire



Runs on CPUs GPUs Adaptive Meshing Different Physics on different meshes



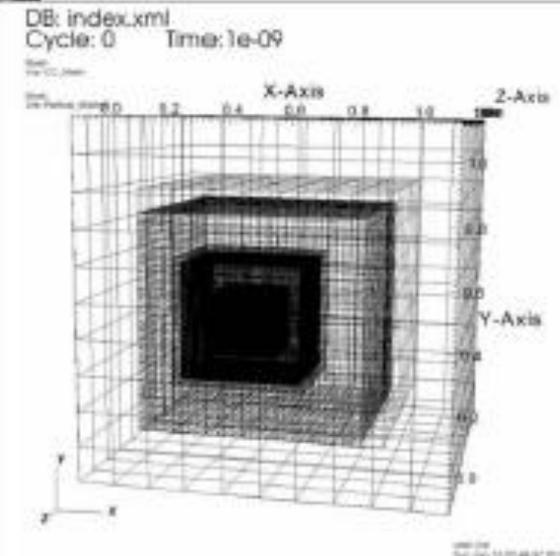
Fluid-structure interaction and AMR Scalable to 256K cores

Different physics on finest mesh – model for MD continuum coupling.

Extend Uintah to include MD on finest meshes

We need to design algorithms and solvers for at least the next decade With 1000x increase in compute power

Source: Peterson



## Technical Challenges:

- **Galli:** Application and development (inc. V&V) of DFT for electrochemical materials of interest to ARL.
- **Kirby:** Exploiting computational savings and accuracy enhancement available through the gPC framework for accomplishing UQ-driven force matching in coarse-graining.
- **Karniadakis:** Accomplishing the first ever attempt at UQ of MD and Mesoscale Modeling.
- 
- **Berzins:** Incorporation of particle-to-particle (direct) interactions into the Uintah Framework for accomplishing MD + Continuum Modeling. Verification of MPM and MD codes in coupled mode.

**Design of new batteries has to bridge molecular level understanding (Li<sup>+</sup> transport, electrochemistry at interfaces, etc.) and the underlying macroscopic structure of composite electrodes and requires:**

- (i) Implementation and validation of hierarchical multiscale modeling approaches with bidirectional bridging.
- (ii) Enhancement of models and methods to accurately capture all key electrochemical and thermophysical processes.
- (iii) Implementation of UQ-driven coarse-graining and scale bridging methodologies.

**Will build on existing multiscale modeling of electrode materials**

Source: Bedrov

## Microanalysis

- SEM/EDXS
- SIMS
- HR TEM
- XRD
- Auger/XPS
- AFM
- FIB
- Micro Raman

## Electro Optics & Photonics

- Time-Resolved Infrared Spectroscopy Facility
- MOCVD, MBE semiconductor growth
  - Indium Phosphide
  - Gallium Nitride
  - Gallium Antimonide
  - Lead Tin Telluride
  - Mercury Cadmium Telluride
  - Gallium Arsenide

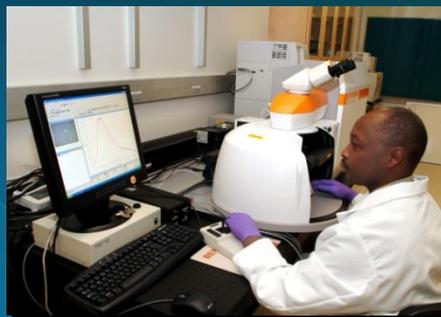
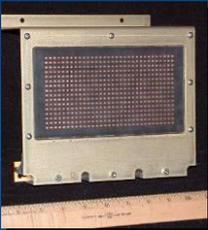
## Specialty Electronic Materials and Sensors Cleanroom

- E-Beam Lithography System
- i-line Lithography
- Lithography Stepper (optical)
- In-Process Material and Device Characterization
- Piece Part to 6" Wafer Capable
- RF Range Facility
- E/B – Field Sensor Suite
- Metal & Dielectric Deposition
- LPCVD High Temperature Processing and Wafer Bonding
- RIE/ICP

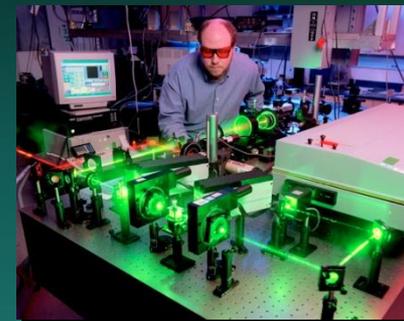
## Power & Energy

- Reformer Lab
- Power Conditioning Lab
- Energy Storage Labs
- Micro Power Lab
- Power MEMS

**Radar, Antenna & MFRF**



**Spectral  
dissection of  
bacteria and  
thin-films**



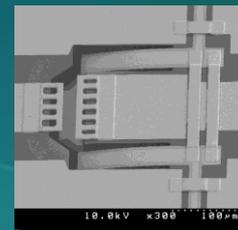
**Non-linear Optics**



**RF Material &  
Devices**



**Electric  
Field Cage  
for sensor  
evaluation**



**NEMS &  
MEMS PZT**



**Device Fabrication  
Advanced RF  
Technology**



**DC-40GHz  
environmental  
cryogenic I/V  
probe station**

**Piezoelectric  
Sputtering for  
MEMS and  
communication  
devices**



**Electronic  
transport  
characterization in  
nano-scale  
structures**

**III-V Etching  
for optical device  
fabrication**



**Device  
Fabrication  
Electro-  
Optics**





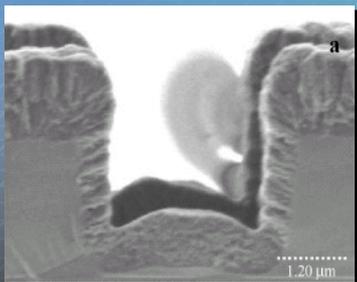
**Jet Vapor Deposition**



**Dry Room for electrochemical cell preparation**



**Power Conditioning Lab**



**SiC device stress analysis evaluations**

**Single and multiple battery cell evaluation laboratories**

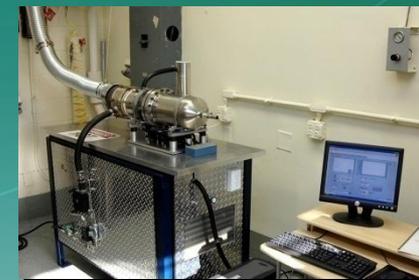


**Isomer Battery Laboratory**



**Electric Drive**

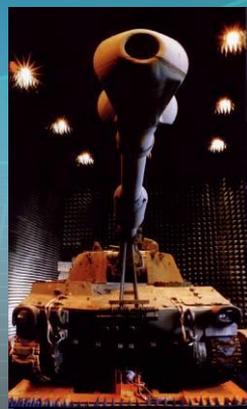
**Fuel Cell evaluations**



**Small Engine Evaluation**



**Air Gun for high-G evaluation**



**High Power RF Anechoic Chamber**



**Fuel Cell Powered Robotic Vehicle**





# Backup